





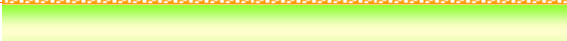






Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
08	220	FR4	35	L20.35_20.105	P10_06	S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

08_220_FR4_35_L20.35_20.105_p10_06_s1

Layers	in μ	Material	Build-Up	Assembly				
Layer-1	35 μ	Copper		} A1				
	60 μ	Prepreg			(60 μ PrePreg-Type: 1080)			
Layer-2	60 μ	Prepreg			} A2			
	35 μ	Copper				(100 μ PrePreg-Type: 2125)		
Layer-4	200 μ	L-FR4				} A3		
	100 μ	Prepreg					(100 μ PrePreg-Type: 2125)	
Layer-5	100 μ	Prepreg					} A4	
	105 μ	Copper						
Layer-6	200 μ	L-FR4						} B
	105 μ	Copper						
Layer-7	100 μ	Prepreg		} A1				
	100 μ	Prepreg						
Layer-9	105 μ	Copper			} A2			
	200 μ	L-FR4						
Layer-99	105 μ	Copper				} A3		
	100 μ	Prepreg						
Layer-99	100 μ	Prepreg					} A4	
	200 μ	L-FR4						
Layer-99	35 μ	Copper						} B
	60 μ	Prepreg						
Layer-99	60 μ	Prepreg		} A1				
	35 μ	Copper						

© Copyright by Printed Circuit Boards GmbH